



## Materials Declaration Form

<b>IPC</b>	1752	<b>Version</b>	2
<b>Form Type *</b>	Distribute		
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

\*: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-01-26
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC10H12WL	H84Z*HC151T7	A	Z45A	2018-01-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	5800	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.92 / 20.93 / 5.02	3	flat	
Comment	Package: DO247 LONG LEADS			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.81	Die / Leadframe	139

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	H842*HC151T7				6000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.760	mg	supplier	die	Silicium carbide	409-21-2		3.560	mg	946809	614
				supplier	metallization	Aluminium (Al)	7429-90-5		0.040	mg	10638	7
				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	1596	1
				supplier	passivation	Nickel (Ni)	7440-02-0		0.032	mg	8510	6
				supplier	metallization	Silver (Ag)	7440-22-4		0.068	mg	18085	12
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	532	0
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	532	0
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1596	1
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.027	mg	7181	5
				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.017	mg	4521	3
Leadframe	Copper & its alloys	1867.388	mg	supplier	alloy	Copper (Cu)	7440-50-8		1863.840	mg	998100	321352
				supplier	alloy	Iron (Fe)	7439-89-6		2.801	mg	1500	483
				supplier	metallization	Nickel (Ni)	7440-02-0		0.747	mg	400	129
Die attach	Other Organic Materials	15.363	mg	supplier	soft solder	Tin (Sn)	7440-31-5		9.986	mg	650003	1722
				supplier	soft solder	Silver (Ag)	7440-22-4		3.841	mg	250017	661
				supplier	soft solder	Antimony (Sb)	7440-36-0		1.536	mg	99980	265
Bonding wire	Aluminum & its alloys	16.659	mg	supplier	wire	Aluminium (Al)	7429-90-5		16.659	mg	1000000	2871
Encapsulation	Other Organic materials	3868.804	mg	supplier	mold compound	Silica ( Fused )	60676-86-0		3578.644	mg	925000	617008
				supplier	mold compound	Flame retardant	proprietary		58.032	mg	15000	10006
				supplier	mold compound	Epoxy resin	25068-38-6		96.720	mg	25000	16676
				supplier	mold compound	Phenol resin	29690-82-2		96.720	mg	25000	16676
				supplier	mold compound	Carbon Black	1333-86-4		38.688	mg	10000	6670
Connection coating	Other inorganic materials	28.026	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		28.026	mg	1000000	4832